

GR 97 P 1903

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Amend
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hansjörg Reichert et al.
Applic. No. : 09/483,737
Filed : January 14, 2000
Title : Method and Apparatus for Producing a Chip-Substrate Connection
Examiner : Ahmed N Sefer
Group Art Unit : 2826

Preliminary Amendment

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Responsive to the final Office action dated May 3, 2002 and prior to continued examination, kindly amend the above-identified application as follows:

In the Claims:

~~Cancel~~ claim 17.

B1
Claim 15(amended). A semiconductor component, comprising:

a solder containing at least two components with at least two metal-containing constituents including a first constituent X